

The applicants respectfully request that the proposed drawing corrections submitted herewith be approved by the Examiner, and that the outstanding objections to the drawings be withdrawn.

IN THE CLAIMS:

Please amend claims 3, 11, 15 and 17 as follows:

Claim 3, line 2, change "claim 1" to --claim 15--.

Claim 11, line 9, change "a bonding head not having heating means" to --a bonding head--.

FI Sub 15. (Amended) A fabrication method of a semiconductor device comprising the steps of:

- (a) forming a plurality of projection electrodes on each of a plurality of semiconductor chips;
- (b) applying a thermosetting insulating adhesive to areas of mounting parts where the semiconductor chips are to be mounted on a substrate;
- (c) heating the thermosetting insulating adhesive on the substrate with a half-thermosetting temperature so as to harden the thermosetting insulating adhesive to a half-

thermosetting state by heating means and, [concurrently] then, aligning the semiconductor chips to the mounting parts of the substrate at a first stage [and performing a first fixing of the semiconductor chips with a first pressure] by a bonding head [not having heating means] to which the semiconductor chips are absorbed;

(d) moving the substrate to a second stage, while the semiconductor chips on the mounting parts of the substrate are held at their position by the half-thermosetting state of the thermosetting insulating adhesive; and

(e) thereafter heating, at the second stage, the substrate, on which the semiconductor chips are fixed, with a thermosetting temperature of the thermosetting insulating adhesive[, and performing a second fixing of the semiconductor chips with a second pressure, wherein the second pressure for performing the second fixing of the semiconductor chips is greater than the first pressure for performing the first fixing of the semiconductor chips].

17. (Amended) A fabrication method according to claim 15, wherein in the heating step (e), heating the thermosetting insulating adhesive [and performing the second fixing of the semiconductor chips are performed] by a heat block having a plurality of pressing/heating heads each of which is provided on the heat block corresponding to the mounting parts of the substrate.